



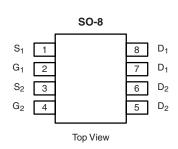
# Dual P-Channel 60-V (D-S) 175° MOSFET

| PRODUCT SUMMARY     |   |                    |  |  |
|---------------------|---|--------------------|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}\left(\Omega\right)$           | I <sub>D</sub> (A) |  |  |
| - 60                | $0.120 \text{ at V}_{GS} = -10 \text{ V}$ | - 3.1              |  |  |
|                     | 0.150 at V <sub>GS</sub> = - 4.5 V        | - 2.8              |  |  |

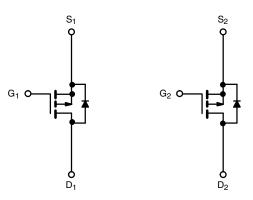
## **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4948BEY-T1-E3 (Lead (Pb)-free) Si4948BEY-T1-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET

P-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b>                                 | T <sub>A</sub> = 25 °C, unle | ss otherwise r                    | noted       |              |      |
|---|------------------------------|-----------------------------------|-------------|--------------|------|
| Parameter   |                              | Symbol                            | 10 s        | Steady State | Unit |
| Drain-Source Voltage  |                              | V <sub>DS</sub>                   | - 60        |              | ٧    |
| Gate-Source Voltage   |                              | V <sub>GS</sub>                   | ± 20        |              |      |
| Continuous Dunin Comment /T 150 °C)                             | T <sub>A</sub> = 25 °C       | - I <sub>D</sub>                  | - 3.1       | - 2.4        |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup> | T <sub>A</sub> = 70 °C       |                                   | - 2.6       | - 2.0        |      |
| Pulsed Drain Current (10 μs Pulse Width)                        |                              | I <sub>DM</sub>                   | - 25        |              | Α    |
| Continuous Source Current (Diode Conduction) <sup>a</sup>       |                              | I <sub>S</sub>                    | - 2         | - 1.1        |      |
| Avalanche Current   | L = 0.1 mH                   | I <sub>AS</sub>                   | 15<br>11    |              |      |
| Single Pulse Avalanche Energy                                   | L = U. I IIII                | E <sub>AS</sub>                   |             |              | mJ   |
| Maximum Power Dissipation <sup>a</sup>                          | T <sub>A</sub> = 25 °C       | P <sub>D</sub>                    | 2.4         | 1.4          | W    |
|   | T <sub>A</sub> = 70 °C       |                                   | 1.7         | 0.95         |      |
| Operating Junction and Storage Temperature Range                |                              | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175 |              | °C   |

| THERMAL RESISTANCE RATINGS               |              |                     |         |         |      |  |
|--|--------------|---------------------|---------|---------|------|--|
| Parameter                                |              | Symbol              | Typical | Maximum | Unit |  |
| Manifesture Installed to Analysis and    | t ≤ 10 s     | - R <sub>thJA</sub> | 53      | 62.5    | °C/W |  |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State |                     | 85      | 110     |      |  |
| Maximum Junction-to-Foot                 | Steady State | $R_{thJF}$          | 30      | 37      |      |  |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

# Vishay Siliconix



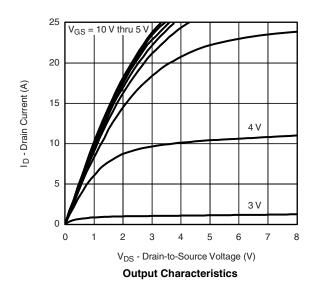
| Parameter                                     | Symbol              | Test Conditions  | Min. | Тур.  | Max.  | Unit |  |
|---|---------------------|--|------|-------|-------|------|--|
| Static  |                     |  |      |       |       |      |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$                                    | - 1  |       | - 3   | V    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                        |      |       | ± 100 | nA   |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V                          | - 1  |       | - 1   |      |  |
|   |                     | V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C  |      |       | - 10  | μΑ   |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>  | V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V                        | - 25 |       |       | Α    |  |
| Drain-Source On-State Resistance <sup>a</sup> | В                   | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.1 A                       |      | 0.100 | 0.120 |      |  |
|   | R <sub>DS(on)</sub> | $V_{GS} = -4.5 \text{ V}, I_D = -0.2 \text{ A}$                          |      | 0.126 | 0.150 | Ω    |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 3.1 A                       |      | 8.5   |       | S    |  |
| Diode Forward Voltage <sup>a</sup>            | $V_{SD}$            | I <sub>S</sub> = - 2 A, V <sub>GS</sub> = 0 V                            |      | - 0.8 | - 1.2 | V    |  |
| Dynamic <sup>b</sup>                          | L                   |  |      |       |       |      |  |
| Total Gate Charge                             | Qg                  |  |      | 14.5  | 22    |      |  |
| Gate-Source Charge                            | Q <sub>gs</sub>     | $V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3.1 \text{ A}$ |      | 2.2   |       | nC   |  |
| Gate-Drain Charge                             | Q <sub>gd</sub>     |  |      | 3.7   |       |      |  |
| Gate Resistance                               | $R_g$               | f = 1 MHz  |      | 14    |       | Ω    |  |
| Turn-On Delay Time                            | t <sub>d(on)</sub>  |  |      | 10    | 15    |      |  |
| Rise Time                                     | t <sub>r</sub>      | $V_{DD}$ = - 30 V, $R_L$ = 30 $\Omega$                                   |      | 15    | 22    |      |  |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> | $I_D\cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_g$ = 6 $\Omega$                 |      | 50    | 75    | ns   |  |
| Fall Time                                     | t <sub>f</sub>      |  |      | 35    | 55    |      |  |
| Source-Drain Reverse Recovery Time            | t <sub>rr</sub>     | I <sub>F</sub> = - 2 A, dl/dt = 100 A/μs                                 |      | 30    | 50    |      |  |

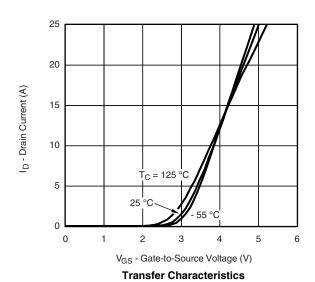
### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

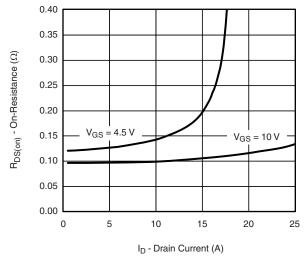




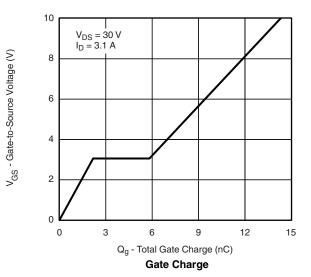


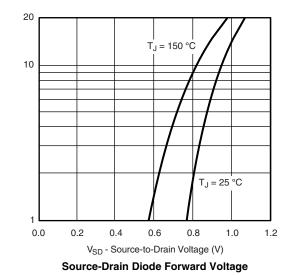


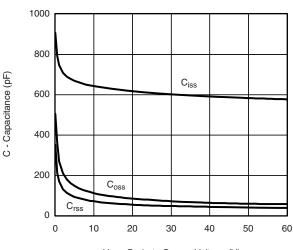
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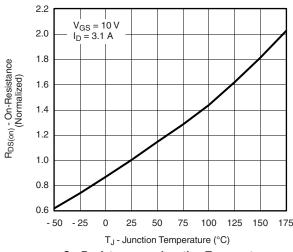
## On-Resistance vs. Drain Current



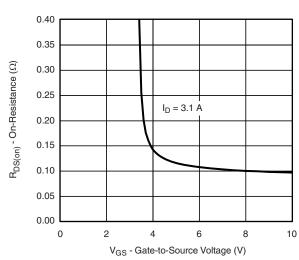




 $V_{DS}$  - Drain-to-Source Voltage (V) **Capacitance** 



On-Resistance vs. Junction Temperature

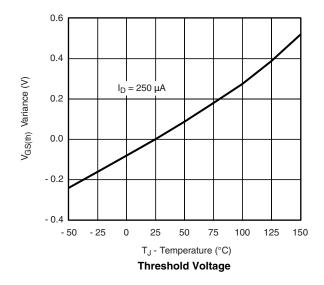


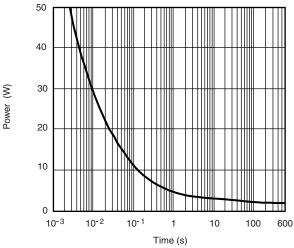
On-Resistance vs. Gate-to-Source Voltage

Is - Source Current (A)

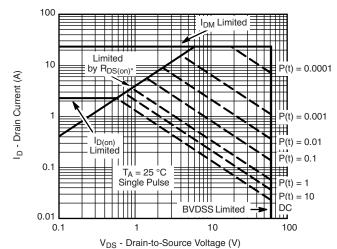
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## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



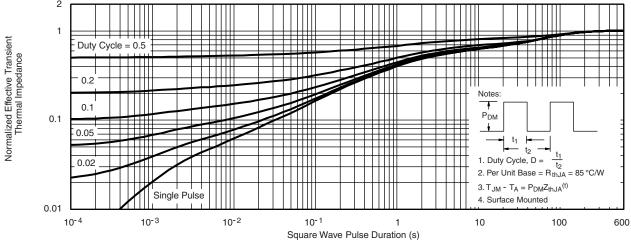


Single Pulse Power



## \* $V_{GS} > \mbox{minimum } V_{GS}$ at which $R_{DS(on)}$ is specified Safe Operating Area, Junction-to-Case

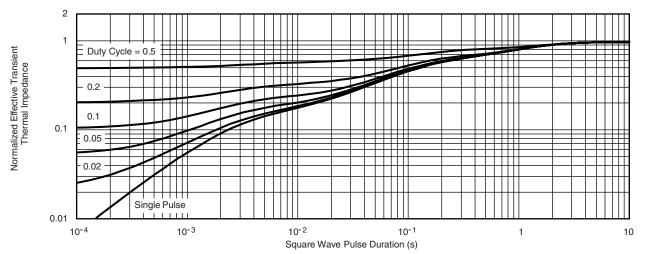
# 2



Normalized Thermal Transient Impedance, Junction-to-Ambient



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

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